

Figure 1
(Prior Art)

RPS9-2000-0103051

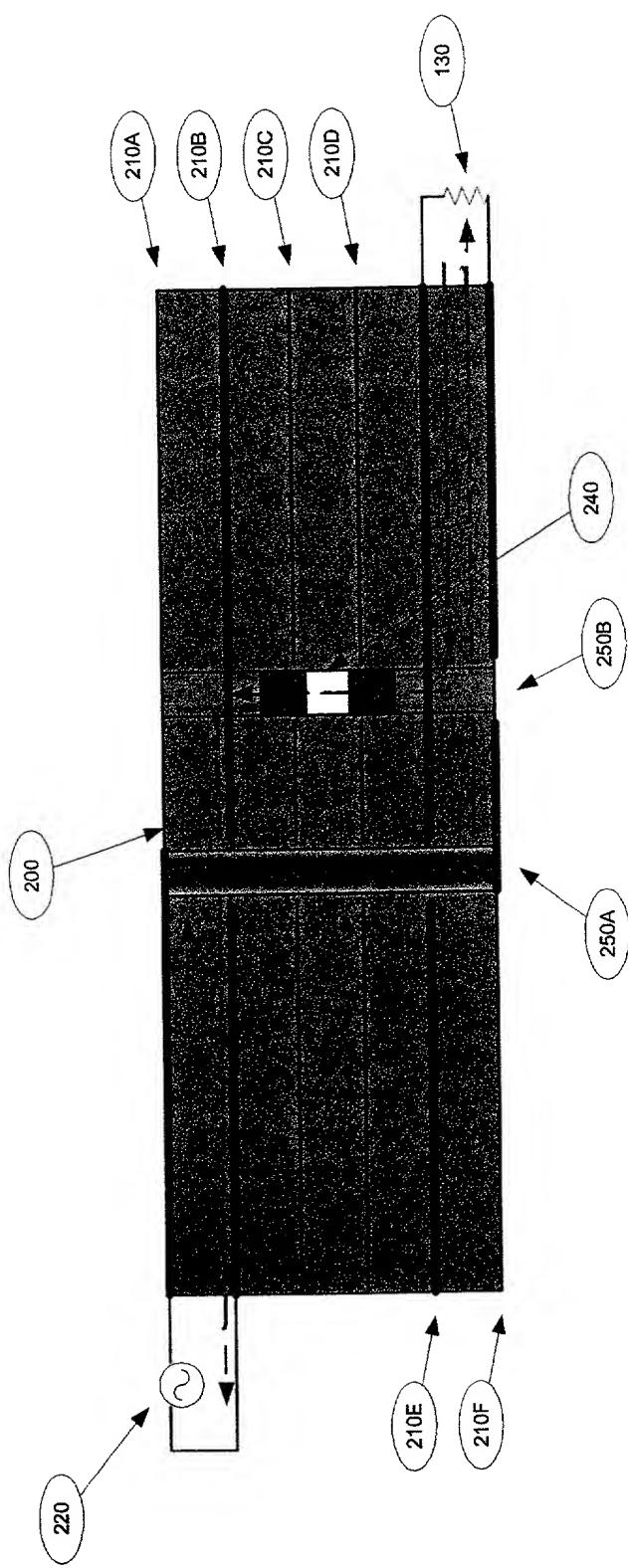


Figure 2

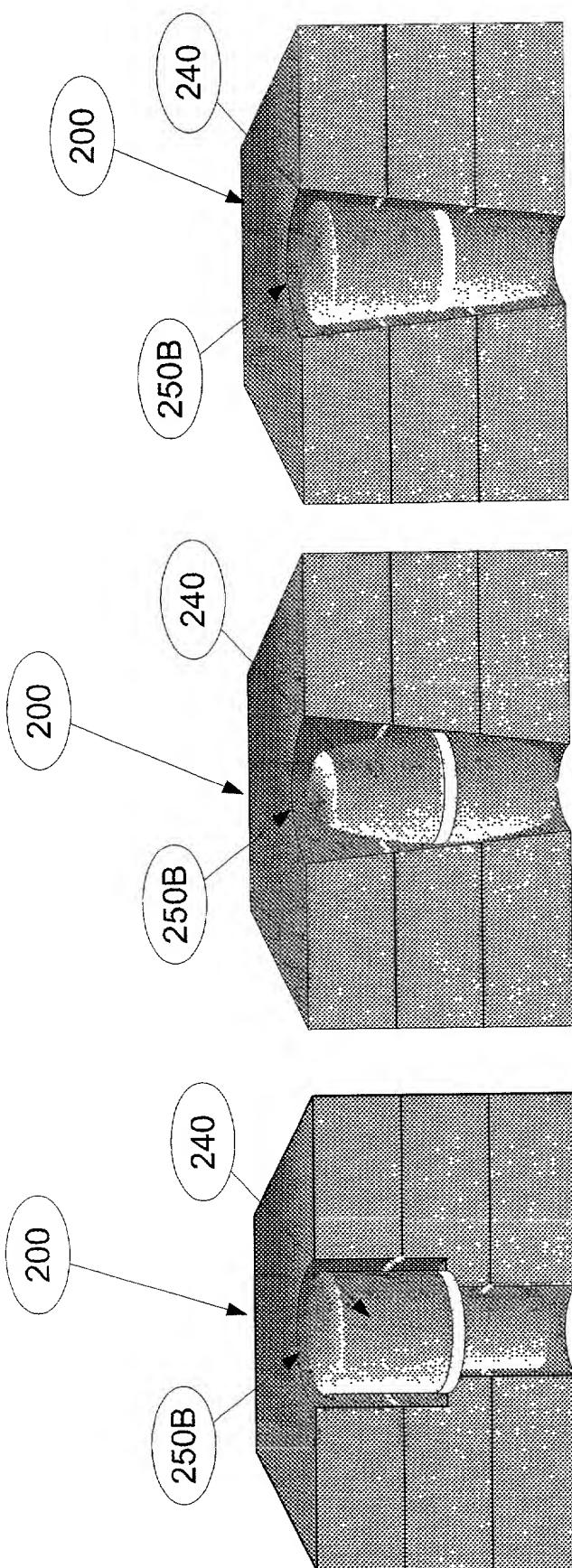


Figure 3A

Figure 3B

Figure 3C

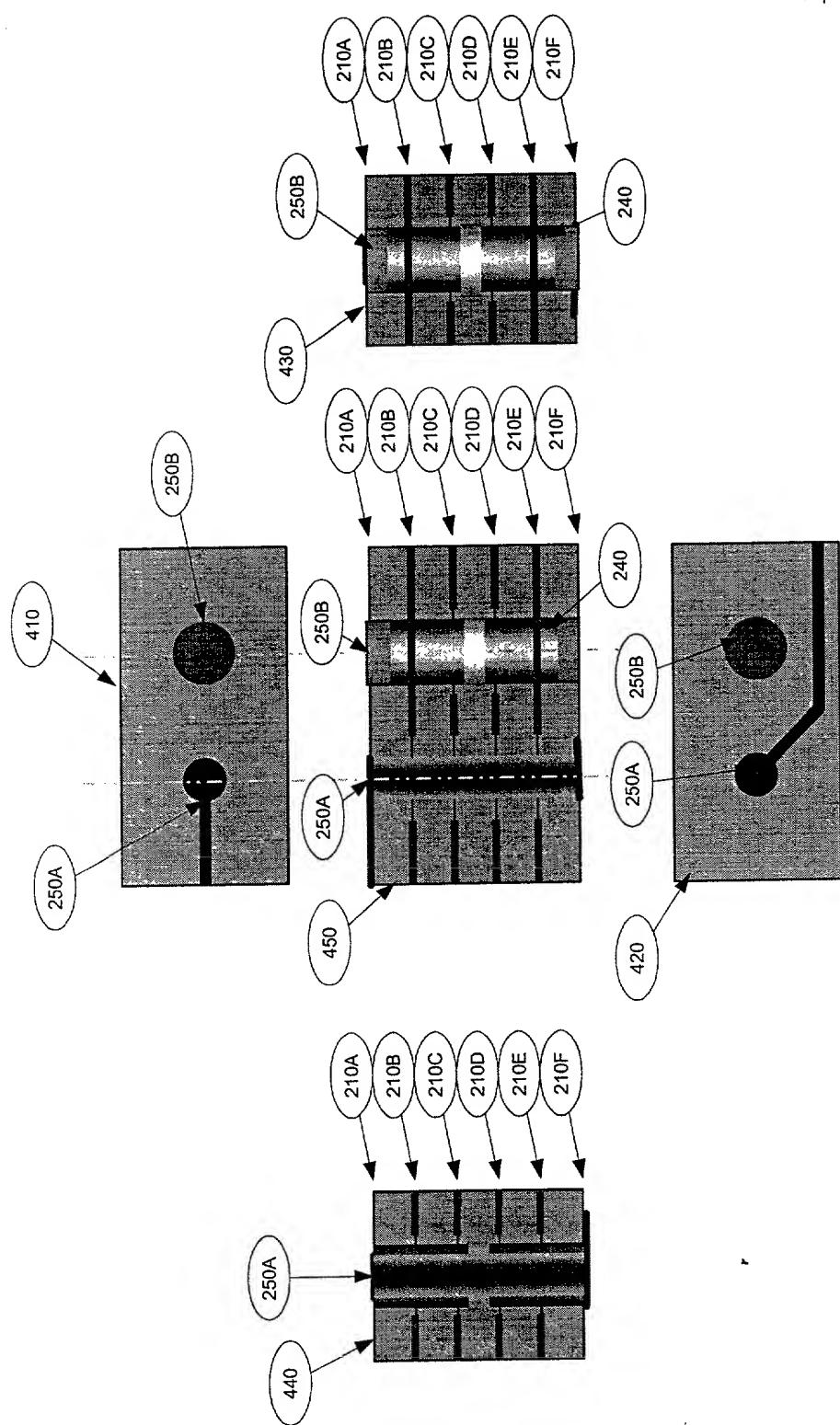


Figure 4

Figure 5

500



570

Forming a printed circuit board comprising a plurality of conductive layers and two or more vias interconnecting two or more conductive layers of the plurality of conductive layers

520

Embedding an electrical component in the via that forms part of the reference path between two separate inner conductive layers of the plurality of conductive layers within the printed circuit board

Figure 6

600



Forming a printed circuit board comprising a plurality of conductive layers and two or more vias interconnecting two or more conductive layers of the plurality of conductive layers

610

Embedding an electrical component in any particular via between any two separate conductive layers of the plurality of conductive layers within the printed circuit board

620